

#### **FEATURES**

- Single Low EMI IC to replace multiple crystals and oscillators on Notebooks and Motherboards (27MHz, 10MHz, 14.318MHz, 8MHz, 12MHz, 24.576MHz, 25MHz).
- Selectable crystal input: 24.576MHz or 14.318MHz (accuracy requirement +/- 20ppm)
- Less than 10ppm Frequency Synthesis error, meeting AC97, IEEE1394, IEEE802 and USB2.0 frequency precision specification.
- 27MHz clock with 5 levels of Selectable Spread
   Spectrum modulation form +/- 0.5% to +/- 1.5% center.
- 25MHz clock with double drive strength (Ethernet PHY and MAC).
- 24.576MHz clocks for Audio Codec and IEEE1394.
- 12MHz for USB 2.0.
- Selectable 10MHz and 8MHz for Keyboard controller.
- Dual power source selection for 24.576MHz, 10MHz, and 12MHz.
- Available in 16-Pin SOIC or TSSOP.

#### Table 1. SPREAD SPECTRUM SELECTION

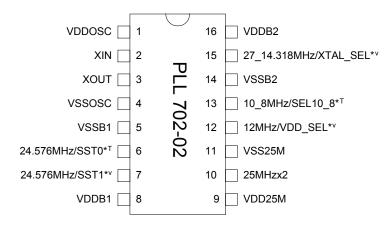
SST1	SST0 SST Modulation only 27MHz. (pin 15)		
1	1	+/- 1.5 %	
1	0	+/- 1.25 %	
1	M	+/- 1 %	
0	1	+/- 0.75 %	
0	0	+/- 0.5 %	
0	M	SST OFF (Default)	

Notes: M = Do not connect. 1 = Pulled up. 0 = Pulled down.

#### **Table 2. POWER SELECTION TABLE**

VDD_SEL	24.576MHz (pin 7)	12MHz (pin 12)
0	VDDB1	VDDB2
1	VDD25M	VDD25M

#### **PIN ASSIGNMENT**



Note: 25MHzx2: double drive strength

\*: Bi-directional pin

v: Internal pull-down resistor (120kΩ)

T: Tri-level input

#### **POWER GROUPS**

- VDDOSC VSSOSC: XIN, XOUT, analog core and digital part.
- VDDB1 VSSB1: 24.576MHz.
- VDDB2 VSSB2: 27MHz, 10 8MHz, and 12MHz.
- VDD25M VSS25M: 25MHz, (10\_8MHz, 12MHz, 24.576MHz when power VDDB1, VDDB2 not present).

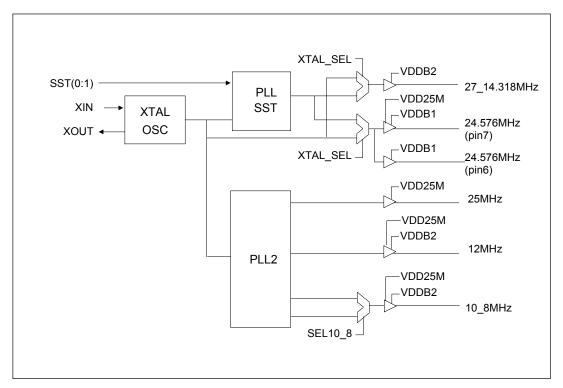
Table 3. FREQUENCY SELECTION TABLE

SEL10 8	10_8MHz ( pin 13 )				
SLL10_0	Power Source	Output Frequency			
М	VDD25M	8MHz			
1	VDDB2	10MHz			
0	OFF	_			

Table 4. CRYSTAL SELECTION TABLE

Crystal Input	XTAL_SEL
24.576MHz	0
14.318MHz	1





Note 1: In order to use VDD25M as power source for 10\_8MHz (pin 13), 24.576MHz (pin 7), and 12MHz (pin 12), it is necessary to select this feature through the VDD\_SEL and SEL10\_8M inputs (see Power Selection and 10\_8MHz Frequency Selection Tables on p.1).

Note 2: Only 27MHz output is modulated for low EMI via Spread Spectrum.



#### PIN DESCRIPTIONS

Name	Pin#	Туре	Description
VDDOSC	1	Р	3.3V power supply for oscillator, analog core and digital circuitry.
XIN	2	I	Crystal input: accepts either 24.576MHz or 14.31818MHz fundamental crystal (CL = 20pF, parallel resonant mode, +/-20ppm). On-chip load capacitors: no external load capacitors required. (See the table #4)
XOUT	3	0	Crystal output.
VSSOSC	4	Р	Ground connection.
VSSB1	5	Р	Ground connection.
24.576MHz/SST0	6	В	Bi-directional and Tri-Level pin. Upon power-on, the value of SST0 is latched in and used to select the SST control (see Spread Spectrum selection table 1). Tri level input: M = Do not connect, 1 = Pull up, 0 = Pull down. After power-up this pin acts as 24.576MHz output clock.
24.576MHz/SST1	7	В	Bi-directional pin. Upon power-on, the value of SST1 is latched in and used to select the SST control (see Spread Spectrum selection table 1). Internal pull down defaults SST1 to 0, use external pull-up to set to 1. After power-up this pin acts as 24.576MHz output clock.
VDDB1	8	Р	3.3V power supply for 24.576MHz clock.
VDD25M	9	Р	3.3V power supply for 25MHz, 10_8MHz, 12MHz, 24.576MHz.
25MHzx2	10	0	25MHz Ethernet output clock (double drive strength).
VSS25M	11	Р	Ground connection.
12MHz/VDD_SEL	12	В	Bi-directional pin. Upon power-on, the value of VDD_SEL is latched in and used to select the power (see Power Selection table 2). Internal pull down defaults SST1 to 0, use external pull-up to set to 1. After power-up this pin acts as 12MHz output clock.
10_8MHz/SEL10_8	13	В	Bi-directional and Tri-level pin. Upon power-on, the value of SEL10_8 is latched in and used to select the output frequency (See frequency selection table 3). Tri level input: M = Do not connect, 1 = Pull up, 0 = Pull down. After power-up this pin acts as 10MHz clock, 8MHz clock, or "No output", depending on SEL10_8.
VSSB2	14	Р	Ground connection.
27_14.318MHz/XTAL_SEL	15	В	Bi-directional pin. Upon power-on, the value of XTAL_SEL is latched in and used to set the input crystal frequency (24.575MHz or 14.31818MHz). Set XTAL_SEL to 0 (default) for 24.576MHz input crystal, set XTAL_SEL to 1 for 14.31818MHz input crystal (see Crystal Selection Table on page 1) After power-up this pin acts as 27MHz output (with 24.576MHz crystal) or as 14.31818MHz pass through clock (with 14.31818MHz crystal), depending on the input crystal.  The 27MHz output can be modulated for low EMI using Spread Spectrum.
VDDB2	16	Р	3.3V power supply for 27MHz, 10MHz, 12MHz, and 24.576MHz.

#### **FUNCTIONAL DESCRIPTION**

# Tri-level and two-level inputs

In order to reduce pin usage, the PLL702-02 uses tri-level input pins. These pins allow 3 levels for input selection: namely, 0 = Connect to GND, 1 = Connect to VDD, M = Do not connect. Thus, unlike the two-level selection pins, the tri-level input pins are in the "M" (mid) state when not connected. In order to connect a tri-level pin to a logical "zero", the pin must be connected to GND. Likewise, in order to connect to a logical "one", the pin must be connected to VDD.



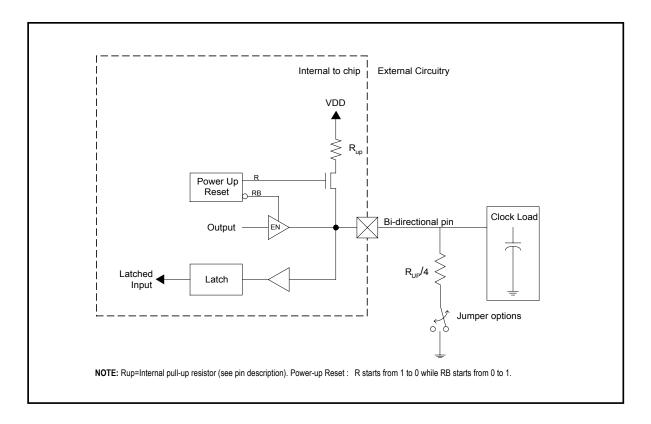
# Connecting a bi-directional pin

The PLL702-02 also uses bi-directional pins. The same pin serves as input upon power-up, and as output as soon as the inputs have been latched. The value of the input is latched-in upon power-up. Depending on the pin (see pin description), the input can be tri-level or a standard two-level. Unlike unidirectional pins, bi-directional pins cannot be connected directly to GND or VDD in order to set the input to "0" or "1", since the pin also needs to serve as output. In the case of two level input pins, an internal pull-up resistor is present. This allows a default value to be set when no external pull down resistor is connected between the pin and GND (by definition, a tri-level input has a the default value of "M" (mid) if it is not connected). In order to connect a bi-directional pin to a non-default value, the input must be connected to GND or VDD through an external pull-down/pull-up resistor.

**Note:** when the output load presents a low impedance in comparison to the internal pull-up resistor, the internal pull-up resistor may not be sufficient to pull the input up to a logical "one", and an external pull-up resistor may be required. For bi-directional inputs, the external loading resistor between the pin and GND has to be sufficiently small (compared to the internal pull-up resistor) so that the pin voltage be pulled below 0.8V (logical "zero"). In order to avoid loading effects when the pin serves as output, the value of the external pull-down resistor should however be kept as large as possible. In general, it is recommended to use an external resistor of around one sixth to one quarter of the internal pull-up resistor (see Application Diagram).

**Note:** when the output is used to drive a load presenting an small resistance between the output pin and VDD, this resistance is in essence connected in parallel to the internal pull-up resistor. In such a case, the external pull-down resistor may have to be dimensioned smaller to guarantee that the pin voltage will be low enough achieve the desired logical "zero". This is particularly true when driving 74FXX TTL components.

#### APPLICATION DIAGRAM: BI-DIRECTIONAL PINS WITH INTERNAL PULL-UP





# **Electrical Specifications**

## 1. Absolute Maximum Ratings

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage Range	Vcc	-0.5	7	V
Input Voltage Range	VI	-0.5	V <sub>CC</sub> +0.5	V
Output Voltage Range	Vo	-0.5	V <sub>CC</sub> +0.5	V
Soldering Temperature			260	°C
Storage Temperature	T <sub>S</sub>	-65	150	°C
Ambient Operating Temperature*	T <sub>A</sub>	-40	85	°C

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

# 2. AC Specification

PARAMETERS	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Input Frequency (to be set via XTAL_SEL)	+/- 20ppm accuracy		14.31818		MHz
input Frequency (to be set via XTAL_SEL)	+/- Zuppili accuracy		24.576		MHz
Output Rise Time	0.8V to 2.0V with no load			1.5	ns
Output Fall Time	2.0V to 0.8V with no load			1.5	ns
Duty Cycle	At VDD/2	45	50	55	%
Duty Cycle 8MHz clock	At VDD/2	43	50	57	%
Max. Absolute Period Jitter	Long term, No SST			150	ps
Max. Jitter, cycle to cycle	Long term + Short term			120	ps

<sup>\*</sup> **Note**: Operating Temperature is guaranteed by design for all parts (COMMERCIAL and INDUSTRIAL), but tested for INDUSTRIAL grade only.

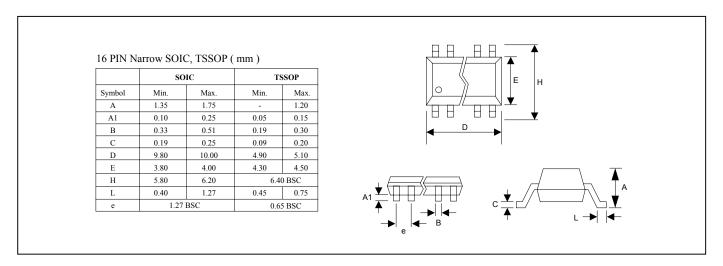


# 3. DC Specification

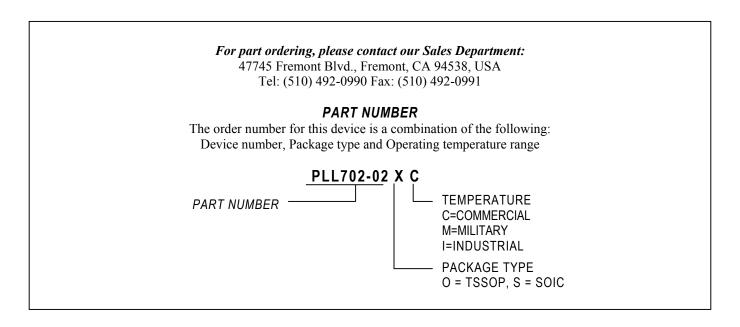
PARAMETERS	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating Voltage	$V_{DD}$	Nominal voltage 3.3V	2.97		3.63	V
Input High Voltage	ViH			V <sub>DD</sub> /2		V
Input Low Voltage	VIL			V <sub>DD</sub> /2	V <sub>DD</sub> /2 - 1	V
Input High Voltage	ViH	For all Tri-level input	V <sub>DD</sub> -0.5			V
Input Low Voltage	VIL	For all Tri-level input			0.5	V
Input High Voltage	ViH	For all normal input	2			V
Input Low Voltage	V <sub>IL</sub>	For all normal input			0.8	V
Output High Voltage	Vон	I <sub>OH</sub> = -30mA (normal drive)	2.4			V
Output High Voltage		I <sub>OH</sub> = -60mA (double drive)				V
Output Low Voltage	VoL	I <sub>OL</sub> = 30mA (normal drive)			0.4	V
		I <sub>OH</sub> = -60mA (double drive)			0.4	V
Output High Voltage At CMOS Level	V <sub>он</sub>	I <sub>OH</sub> = -8mA	V <sub>DD</sub> -0.4			V
Naminal Output Compat	Гоит	Normal drive strength	30			mA
Nominal Output Current		Double drive strength	60			
Operating Supply Current	I <sub>DD</sub>	No Load		17		mA
Short-circuit Current	Is			±100		mA



### **PACKAGE INFORMATION**



#### ORDERING INFORMATION



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